

Customer Code : _____

DATASHEET

DAPU P/N: OS754-A319-8.00MHz-A**Y75NNM08000**

DAPU			Customer Approval
Drew	Audited	Approved	Stamp, please! Thanks!
Date: 2015.12.17			

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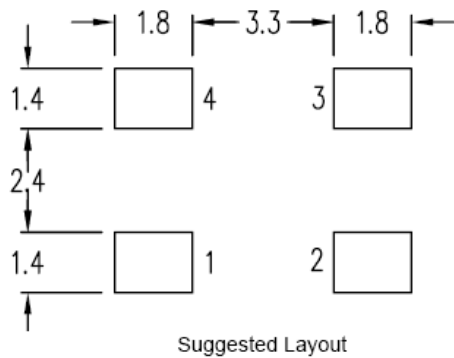


1、 Electrical Parameters

Parameters	SYM	Electrical Spec.				Notes
		Min.	Typ.	Max.	Units	
Frequency Stabilities						
Nominal Frequency	F _N	8.00			MHz	
Oscillation mode		Fundamental				
Frequency Stability		-30		+30	× 10 ⁻⁶	incl. 25 °C tolerance, tolerance over operating temperature range, input voltage change, load change, 1 year aging.
Vs. aging /1.year		-3		+3	× 10 ⁻⁶	
RF Output						
Output Waveform		CMOS				
Load	I _{OUT}	15			pF	
Output Voltage High	V _{OH}	90% V _{CC}			V	
Output Voltage Low	V _{OL}			10% V _{CC}	V	
Rise / Fall Time	T _r / T _f			10	ns	
Symmetry	SYM	50 ± 10%				
Start-up Time	T _S			3	ms	
Supply Voltage						
Supply Voltage	V _{CC}	3.3 ± 10%			V	
Input Current	I _{CC}			10	mA	
Standby Current	V _C			10	uA	
Enable Control						
Enable Control		Pin 1				
Phase Noise						
Jitter				1	ps	RMS(12KHz to 20MHz)
Environmental Conditions						
Operating Temperature	T _{OP}	-40	~	85	°C	
Storage Temperature	T _{ST}	-55	~	125	°C	
Temperature Cycle	GB/T 2423.22-2002, Method Nb. Frequency change after test ≤ ±5ppm.					
Low Temperature Storage	GB/T 2423.1-2001, Method Aa. Frequency change after test ≤ ±5ppm.					
High Temperature Storage	GB/T 2423.2-2001, Method Ba. Frequency change after test ≤ ±5ppm.					
Humidity	GB/T 2423.3-2006, Method Cab. Frequency change after test ≤ ±5ppm.					
Vibration	GB/T 2423.10-1995, Method Fc. Frequency change after test ≤ ±5ppm.					
Shock	GB/T 2423.5-1995, Method Ea. Frequency change after test ≤ ±5ppm. No visible damages.					
Drop	GB/T 2423.8-1995, Method Ed. Frequency change after test ≤ ±5ppm. No visible damages.					
Solderability	GB/T 2423.28-2005, Method Tc. Terminals shall be covered more then 95% with solder.					
Terminal Strength	JIS-C-6429 Method 1 & 2. No visible damages.					
Resistance to Soldering Heat	GB/T 2423.28-2005, Test Tb Method 1B. Frequency change after test ≤ ±5ppm.					

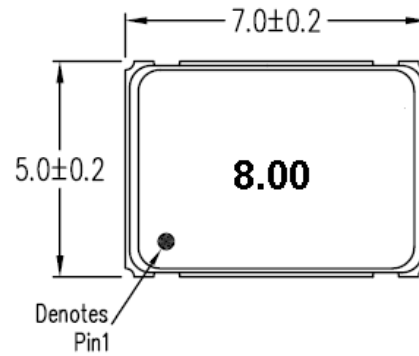
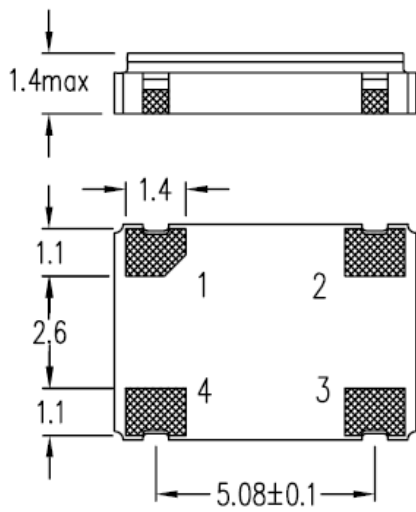


2、 Mechanical Structure(mm)



PIN CONNECTION

1	Enable/Disable*
2	GND
3	Output
4	VDD



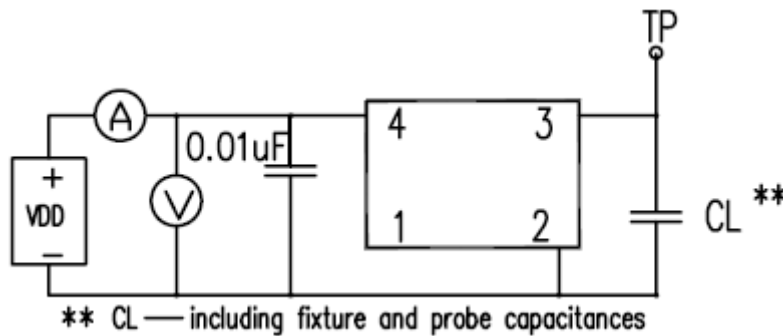
Note1: Tolerance $\pm 0.20\text{mm}$ without mark

Note2: Referential Weight 0.3g

Note3: Enable/disable functional description

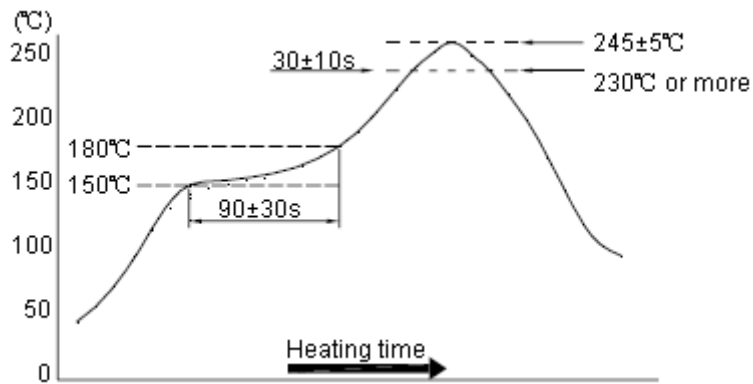
When pin1 goes high ($\geq 0.7\text{VDD}$) or open , the oscillator in normal operation and has output in frequency .When pin1 goes low ($\leq 0.3\text{VDD}$) , the oscillator stops and the oscillator output (pin3) becomes high impedance.

3、 Test circuit

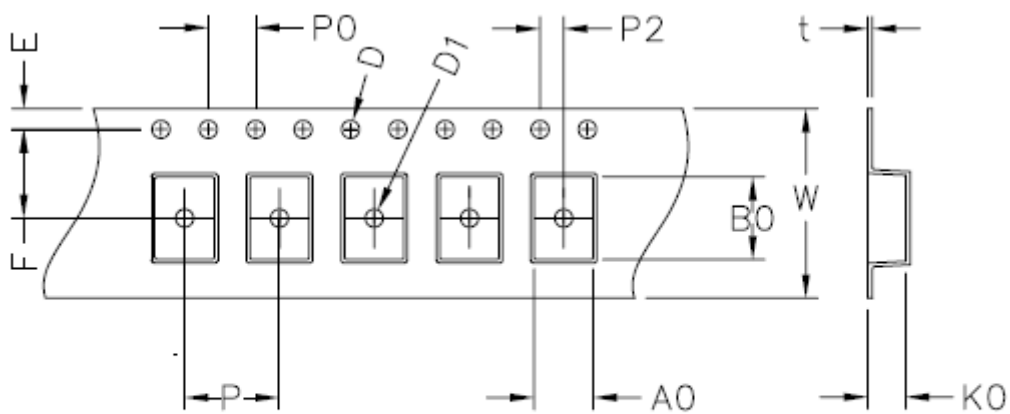




4、 Reflow Soldering Curve (RoHS)



5、 Package: Tape & Reel (mm)



EMBOSSED TYPE DIMENSIONS

ITEM	W+0.3/0.1	A0±0.1	B0±0.1	K0±0.1	P±0.1	F±0.1	t±0.05	Qty
149	16.0	5.5	7.5	2.0	8.0	7.5	0.3	1000

E=1.75±0.1、D=1.5±0.1、D1=1.5+0.25/-0.0、P0=4.0±0.1、P2=2.0±0.1